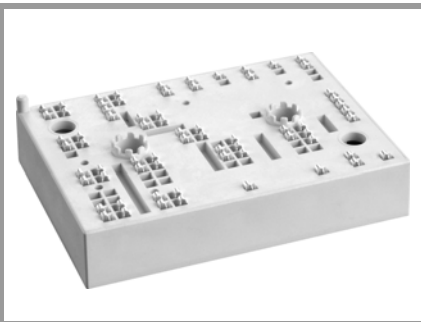


# SKiiP 37NAB12T7V1



MiniSKiiP® 3

## 3-phase Converter-Inverter-Brake (CIB)

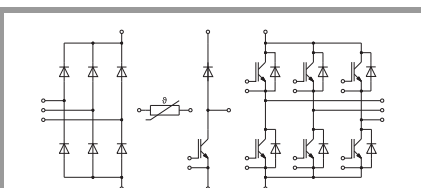
### SKiiP 37NAB12T7V1

#### Features\*

- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- New SKR PEP diode technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

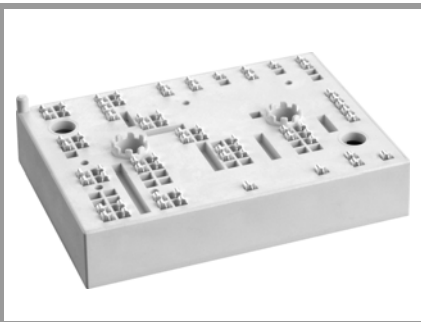
- Max. case temperature limited to  $T_C=T_S=125\text{ °C}$
- Product reliability results valid for  $T_j \leq 150\text{ °C}$  (recommended  $T_{j,op} = -40 \dots +150\text{ °C}$ )
- MiniSKiiP “Technical Explanations” and “Mounting Instructions” are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document: “Technical Explanations Thermal Interface Materials”
- Inverter IGBT: T1 – T6
- Chopper IGBT: T14
- Inverse Diode: D1 – D6
- Freewheeling Diode: D13
- Rectifier Diode: D7 – D12



NAB

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
<b>Inverter - IGBT</b>				
$V_{CES}$	$T_j = 25\text{ °C}$		1200	V
$I_C$	$\lambda_{paste}=0.8\text{ W/(mK)}$	$T_s = 70\text{ °C}$	76	A
		$T_j = 175\text{ °C}$	62	A
$I_C$	$\lambda_{paste}=2.5\text{ W/(mK)}$	$T_s = 70\text{ °C}$	89	A
		$T_j = 175\text{ °C}$	72	A
$I_{Chom}$			75	A
$I_{CRM}$			150	A
$V_{GES}$			-20 ... 20	V
$t_{psc}$	$V_{CC} = 800\text{ V}$ $V_{GE} \leq 15\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 175\text{ °C}$	7	$\mu\text{s}$
$T_j$			-40 ... 175	$^{\circ}\text{C}$
<b>Chopper - IGBT</b>				
$V_{CES}$	$T_j = 25\text{ °C}$		1200	V
$I_C$	$\lambda_{paste}=0.8\text{ W/(mK)}$	$T_s = 70\text{ °C}$	76	A
		$T_j = 175\text{ °C}$	62	A
$I_C$	$\lambda_{paste}=2.5\text{ W/(mK)}$	$T_s = 70\text{ °C}$	89	A
		$T_j = 175\text{ °C}$	72	A
$I_{Chom}$			75	A
$I_{CRM}$			150	A
$V_{GES}$			-20 ... 20	V
$t_{psc}$	$V_{CC} = 800\text{ V}$ $V_{GE} \leq 15\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 175\text{ °C}$	7	$\mu\text{s}$
$T_j$			-40 ... 175	$^{\circ}\text{C}$
<b>Inverse - Diode</b>				
$V_{RRM}$	$T_j = 25\text{ °C}$		1200	V
$I_F$	$\lambda_{paste}=0.8\text{ W/(mK)}$	$T_s = 70\text{ °C}$	56	A
		$T_j = 175\text{ °C}$	45	A
$I_F$	$\lambda_{paste}=2.5\text{ W/(mK)}$	$T_s = 70\text{ °C}$	64	A
		$T_j = 175\text{ °C}$	51	A
$I_{FRM}$			150	A
$I_{FSM}$	$t_p = 10\text{ ms, sin } 180^{\circ}, T_j = 150\text{ °C}$		430	A
$T_j$			-40 ... 175	$^{\circ}\text{C}$
<b>Freewheeling - Diode</b>				
$V_{RRM}$	$T_j = 25\text{ °C}$		1200	V
$I_F$	$\lambda_{paste}=0.8\text{ W/(mK)}$	$T_s = 70\text{ °C}$	56	A
		$T_j = 175\text{ °C}$	45	A
$I_F$	$\lambda_{paste}=2.5\text{ W/(mK)}$	$T_s = 70\text{ °C}$	64	A
		$T_j = 175\text{ °C}$	51	A
$I_{FRM}$			150	A
$I_{FSM}$	$t_p = 10\text{ ms, sin } 180^{\circ}, T_j = 150\text{ °C}$		430	A
$T_j$			-40 ... 175	$^{\circ}\text{C}$

# SKiiP 37NAB12T7V1



MiniSKiiP® 3

## 3-phase Converter-Inverter-Brake (CIB)

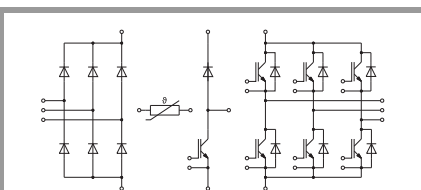
### SKiiP 37NAB12T7V1

#### Features\*

- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- New SKR PEP diode technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

- Max. case temperature limited to  $T_C=T_S=125\text{ °C}$
- Product reliability results valid for  $T_j \leq 150\text{ °C}$  (recommended  $T_{j,op} = -40 \dots +150\text{ °C}$ )
- MiniSKiiP “Technical Explanations” and “Mounting Instructions” are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document: “Technical Explanations Thermal Interface Materials”
- Inverter IGBT: T1 – T6
- Chopper IGBT: T14
- Inverse Diode: D1 – D6
- Freewheeling Diode: D13
- Rectifier Diode: D7 – D12

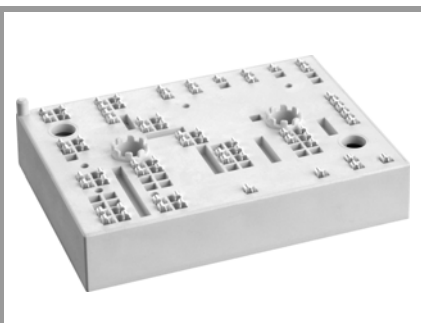


NAB

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
<b>Rectifier - Diode</b>				
$V_{RRM}$	$T_j = 25\text{ °C}$		1600	V
$I_F$	$\lambda_{paste} = 0.8\text{ W/(mK)}$	$T_s = 70\text{ °C}$	84	A
		$T_s = 100\text{ °C}$	66	A
$I_F$	$\lambda_{paste} = 2.5\text{ W/(mK)}$	$T_s = 70\text{ °C}$	95	A
		$T_s = 100\text{ °C}$	74	A
$I_{FSM}$	$t_p = 10\text{ ms}$ $\sin 180^\circ$	$T_j = 25\text{ °C}$	635	A
		$T_j = 150\text{ °C}$	490	A
$i^2t$	$t_p = 10\text{ ms}$ $\sin 180^\circ$	$T_j = 25\text{ °C}$	2000	$A^2s$
		$T_j = 150\text{ °C}$	1200	$A^2s$
$T_j$			-40 ... 175	$^{\circ}C$
<b>Module</b>				
$I_{t(RMS)}$	$T_{terminal} = 80\text{ °C}$ , 20 A per spring		80	A
$T_{stg}$	module without TIM		-40 ... 125	$^{\circ}C$
$V_{isol}$	AC sinus 50 Hz, 1 min		2500	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverter - IGBT</b>						
$V_{CE(sat)}$	$I_C = 75\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25\text{ °C}$		1.55	1.70	V
		$T_j = 150\text{ °C}$		1.72	1.96	V
		$T_j = 175\text{ °C}$		1.75	2.01	V
$V_{CE0}$	chipelevel	$T_j = 25\text{ °C}$		0.90	1.00	V
		$T_j = 150\text{ °C}$		0.75	0.83	V
		$T_j = 175\text{ °C}$		0.72	0.80	V
$r_{CE}$	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25\text{ °C}$		8.7	9.3	$m\Omega$
		$T_j = 150\text{ °C}$		13	15	$m\Omega$
		$T_j = 175\text{ °C}$		14	16	$m\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 1.7\text{ mA}$		5.15	5.8	6.45	V
$I_{CES}$	$V_{GE} = 0\text{ V}$ , $V_{CE} = 1200\text{ V}$ , $T_j = 25\text{ °C}$				1	mA
$C_{ies}$	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		15.10		nF
$C_{oes}$				0.19		nF
$C_{res}$				0.54		nF
$Q_G$	$V_{GE} = -8\text{ V} \dots +15\text{ V}$			1050		nC
$R_{Gint}$	$T_j = 25\text{ °C}$			2.0		$\Omega$
$t_{d(on)}$	$V_{CC} = 600\text{ V}$ $I_C = 75\text{ A}$ $R_{G on} = 2.3\text{ }\Omega$ $R_{G off} = 2.3\text{ }\Omega$	$T_j = 25\text{ °C}$		137		ns
		$T_j = 150\text{ °C}$		142		ns
		$T_j = 175\text{ °C}$		142		ns
$t_r$	$V_{GE} = +15/-15\text{ V}$	$T_j = 25\text{ °C}$		35		ns
		$T_j = 150\text{ °C}$		41		ns
		$T_j = 175\text{ °C}$		44		ns
$E_{on}$	@ $T_j = 150\text{ °C}$ : $di/dt_{on} = 1940\text{ A}/\mu\text{s}$ $di/dt_{off} = 780\text{ A}/\mu\text{s}$ $dv/dt = 3650\text{ V}/\mu\text{s}$	$T_j = 25\text{ °C}$		6		mJ
		$T_j = 150\text{ °C}$		8.5		mJ
		$T_j = 175\text{ °C}$		9		mJ

# SKiiP 37NAB12T7V1



MiniSKiiP® 3

## 3-phase Converter-Inverter-Brake (CIB)

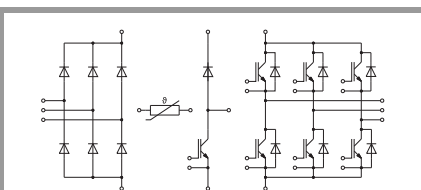
### SKiiP 37NAB12T7V1

#### Features\*

- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- New SKR PEP diode technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

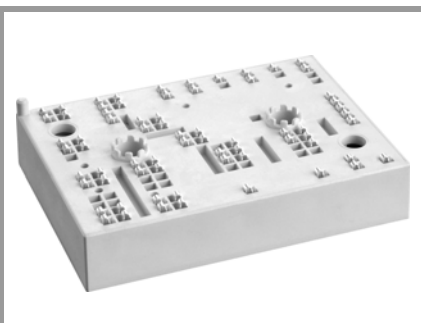
- Max. case temperature limited to  $T_C=T_S=125\text{ °C}$
- Product reliability results valid for  $T_j \leq 150\text{ °C}$  (recommended  $T_{j,op} = -40 \dots +150\text{ °C}$ )
- MiniSKiiP “Technical Explanations” and “Mounting Instructions” are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document: “Technical Explanations Thermal Interface Materials”
- Inverter IGBT: T1 – T6
- Chopper IGBT: T14
- Inverse Diode: D1 – D6
- Freewheeling Diode: D13
- Rectifier Diode: D7 – D12



NAB

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverter - IGBT</b>						
$t_{d(off)}$	$V_{CC} = 600\text{ V}$ $I_C = 75\text{ A}$ $R_{G\ on} = 2.3\ \Omega$ $R_{G\ off} = 2.3\ \Omega$ $V_{GE} = +15/-15\text{ V}$	$T_j = 25\text{ °C}$		250		ns
		$T_j = 150\text{ °C}$		340		ns
		$T_j = 175\text{ °C}$		365		ns
$t_f$		$T_j = 25\text{ °C}$		56		ns
		$T_j = 150\text{ °C}$		86		ns
		$T_j = 175\text{ °C}$		103		ns
$E_{off}$	@ $T_j = 150\text{ °C}$ : $di/dt_{on} = 1940\text{ A}/\mu\text{s}$ $di/dt_{off} = 780\text{ A}/\mu\text{s}$ $dv/dt = 3650\text{ V}/\mu\text{s}$	$T_j = 25\text{ °C}$		4.7		mJ
		$T_j = 150\text{ °C}$		8.1		mJ
		$T_j = 175\text{ °C}$		8.8		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$			0.68		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$			0.53		K/W
<b>Chopper - IGBT</b>						
$V_{CE(sat)}$	$I_C = 75\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25\text{ °C}$		1.55	1.70	V
		$T_j = 150\text{ °C}$		1.72	1.96	V
		$T_j = 175\text{ °C}$		1.75	2.01	V
$V_{CE0}$	chipelevel	$T_j = 25\text{ °C}$		0.90	1.00	V
		$T_j = 150\text{ °C}$		0.75	0.83	V
		$T_j = 175\text{ °C}$		0.72	0.80	V
$r_{CE}$	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25\text{ °C}$		8.7	9.3	m $\Omega$
		$T_j = 150\text{ °C}$		13	15	m $\Omega$
		$T_j = 175\text{ °C}$		14	16	m $\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 1.7\text{ mA}$		5.15	5.8	6.45	V
$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}, T_j = 25\text{ °C}$				1	mA
$C_{ies}$	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		15.10		nF
$C_{oes}$		$f = 1\text{ MHz}$		0.19		nF
$C_{res}$		$f = 1\text{ MHz}$		0.54		nF
$Q_G$	$V_{GE} = -8\text{ V} \dots +15\text{ V}$			1050		nC
$R_{Gint}$	$T_j = 25\text{ °C}$			2.0		$\Omega$
$t_{d(on)}$		$T_j = 25\text{ °C}$		137		ns
		$T_j = 150\text{ °C}$		142		ns
		$T_j = 175\text{ °C}$		142		ns
$t_r$	$V_{CC} = 600\text{ V}$ $I_C = 75\text{ A}$ $R_{G\ on} = 2.3\ \Omega$ $R_{G\ off} = 2.3\ \Omega$ $V_{GE} = +15/-15\text{ V}$	$T_j = 25\text{ °C}$		35		ns
		$T_j = 150\text{ °C}$		41		ns
		$T_j = 175\text{ °C}$		44		ns
$E_{on}$		$T_j = 25\text{ °C}$		6		mJ
		$T_j = 150\text{ °C}$		8.5		mJ
		$T_j = 175\text{ °C}$		9		mJ
$t_{d(off)}$		$T_j = 25\text{ °C}$		250		ns
		$T_j = 150\text{ °C}$		340		ns
		$T_j = 175\text{ °C}$		365		ns
$t_f$	@ $T_j = 150\text{ °C}$ : $di/dt_{on} = 1940\text{ A}/\mu\text{s}$ $di/dt_{off} = 780\text{ A}/\mu\text{s}$ $dv/dt = 3650\text{ V}/\mu\text{s}$	$T_j = 25\text{ °C}$		56		ns
		$T_j = 150\text{ °C}$		86		ns
		$T_j = 175\text{ °C}$		103		ns
$E_{off}$		$T_j = 25\text{ °C}$		4.7		mJ
		$T_j = 150\text{ °C}$		8.1		mJ
		$T_j = 175\text{ °C}$		8.8		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$			0.68		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$			0.53		K/W

# SKiiP 37NAB12T7V1



MiniSKiiP® 3

## 3-phase Converter-Inverter-Brake (CIB)

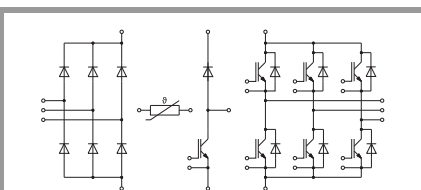
### SKiiP 37NAB12T7V1

#### Features\*

- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- New SKR PEP diode technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

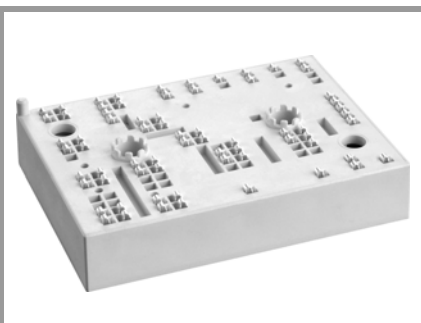
- Max. case temperature limited to  $T_C=T_S=125\text{ °C}$
- Product reliability results valid for  $T_j \leq 150\text{ °C}$  (recommended  $T_{j,op} = -40 \dots +150\text{ °C}$ )
- MiniSKiiP “Technical Explanations” and “Mounting Instructions” are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document: “Technical Explanations Thermal Interface Materials”
- Inverter IGBT: T1 – T6
- Chopper IGBT: T14
- Inverse Diode: D1 – D6
- Freewheeling Diode: D13
- Rectifier Diode: D7 – D12



NAB

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverse - Diode</b>						
$V_F = V_{EC}$	$I_F = 75\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25\text{ °C}$		2.17	2.49	V
		$T_j = 150\text{ °C}$		2.11	2.42	V
		$T_j = 175\text{ °C}$		1.96	2.27	V
$V_{F0}$	chipelevel	$T_j = 25\text{ °C}$		1.30	1.50	V
		$T_j = 150\text{ °C}$		0.90	1.10	V
		$T_j = 175\text{ °C}$		0.82	0.98	V
$r_F$	chipelevel	$T_j = 25\text{ °C}$		12	13	mΩ
		$T_j = 150\text{ °C}$		16	18	mΩ
		$T_j = 175\text{ °C}$		15	17	mΩ
$I_{RRM}$		$T_j = 25\text{ °C}$		50		A
		$T_j = 150\text{ °C}$		67		A
		$T_j = 175\text{ °C}$		80		A
$Q_{rr}$	$V_{CC} = 600\text{ V}$ $I_F = 75\text{ A}$ $V_{GE} = -15\text{ V}$	$T_j = 25\text{ °C}$		4		μC
		$T_j = 150\text{ °C}$		11.6		μC
		$T_j = 175\text{ °C}$		12.2		μC
$E_{rr}$	@ $T_j = 150\text{ °C}$ : $di/dt_{off} = 1930\text{ A/μs}$	$T_j = 25\text{ °C}$		1.4		mJ
		$T_j = 150\text{ °C}$		4.5		mJ
		$T_j = 175\text{ °C}$		6		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8\text{ W/(mK)}$			0.96		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5\text{ W/(mK)}$			0.8		K/W
<b>Freewheeling - Diode</b>						
$V_F = V_{EC}$	$I_F = 75\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25\text{ °C}$		2.17	2.49	V
		$T_j = 150\text{ °C}$		2.11	2.42	V
		$T_j = 175\text{ °C}$		1.96	2.27	V
$V_{F0}$	chipelevel	$T_j = 25\text{ °C}$		1.30	1.50	V
		$T_j = 150\text{ °C}$		0.90	1.10	V
		$T_j = 175\text{ °C}$		0.82	0.98	V
$r_F$	chipelevel	$T_j = 25\text{ °C}$		12	13	mΩ
		$T_j = 150\text{ °C}$		16	18	mΩ
		$T_j = 175\text{ °C}$		15	17	mΩ
$I_{RRM}$		$T_j = 25\text{ °C}$		50		A
		$T_j = 150\text{ °C}$		67		A
		$T_j = 175\text{ °C}$		80		A
$Q_{rr}$	$V_{CC} = 600\text{ V}$ $I_F = 75\text{ A}$ $V_{GE} = -15\text{ V}$	$T_j = 25\text{ °C}$		4		μC
		$T_j = 150\text{ °C}$		11.6		μC
		$T_j = 175\text{ °C}$		12.2		μC
$E_{rr}$	@ $T_j = 150\text{ °C}$ : $di/dt_{off} = 1930\text{ A/μs}$	$T_j = 25\text{ °C}$		1.4		mJ
		$T_j = 150\text{ °C}$		4.5		mJ
		$T_j = 175\text{ °C}$		6		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8\text{ W/(mK)}$			0.96		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5\text{ W/(mK)}$			0.8		K/W

# SKiiP 37NAB12T7V1



MiniSKiiP® 3

## 3-phase Converter-Inverter-Brake (CIB)

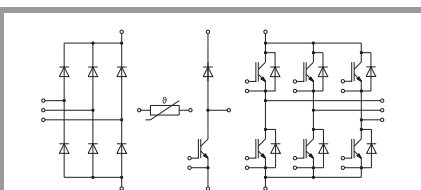
### SKiiP 37NAB12T7V1

#### Features\*

- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- New SKR PEP diode technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

- Max. case temperature limited to  $T_C=T_S=125\text{ °C}$
- Product reliability results valid for  $T_j \leq 150\text{ °C}$  (recommended  $T_{j,op} = -40 \dots +150\text{ °C}$ )
- MiniSKiiP “Technical Explanations” and “Mounting Instructions” are part of the data sheet. Please refer to both documents for further information.
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- Inverter IGBT: T1 – T6
- Chopper IGBT: T14
- Inverse Diode: D1 – D6
- Freewheeling Diode: D13
- Rectifier Diode: D7 – D12



NAB

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Rectifier - Diode</b>						
$V_F$	$I_F = 26\text{ A}$ chiplevel	$T_j = 25\text{ °C}$		0.97	1.20	V
		$T_j = 150\text{ °C}$		0.84	1.07	V
		$T_j = 175\text{ °C}$		0.82	1.05	V
$V_{F0}$	chiplevel	$T_j = 25\text{ °C}$		0.89	1.09	V
		$T_j = 150\text{ °C}$		0.73	0.92	V
		$T_j = 175\text{ °C}$		0.69	0.88	V
$r_F$	chiplevel	$T_j = 25\text{ °C}$		3.1	4.2	mΩ
		$T_j = 150\text{ °C}$		4.4	5.9	mΩ
		$T_j = 175\text{ °C}$		5.0	6.5	mΩ
$I_R$	$T_j = 150\text{ °C}, V_{RRM}$				1.7	mA
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8\text{ W/(mK)}$			0.87		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5\text{ W/(mK)}$			0.74		K/W
<b>Module</b>						
$M_s$	to heat sink		2		2.5	Nm
w				82		g
$L_{CE}$				-		nH
<b>Temperature Sensor</b>						
$R_{100}$	$T_j=100\text{ °C}$ ( $R_{25}=1000\Omega$ )			$1670 \pm 3\%$		Ω
$R_{(T)}$	$R_{(T)}=1000\Omega[1+A(T-25\text{ °C})+B(T-25\text{ °C})^2]$ , $A = 7.635 \cdot 10^{-3}\text{ °C}^{-1}$ , $B = 1.731 \cdot 10^{-5}\text{ °C}^{-2}$					

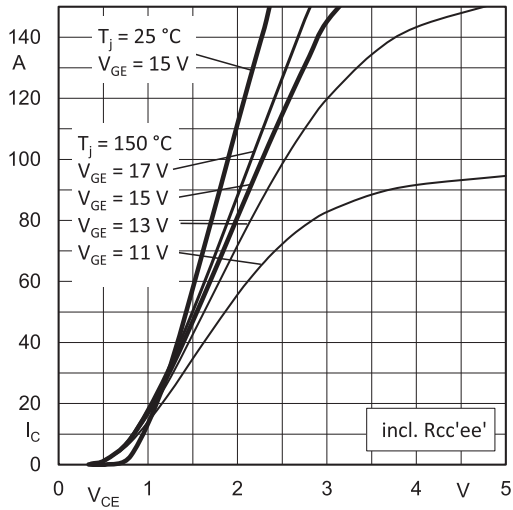


Fig. 1: Typ. output characteristic

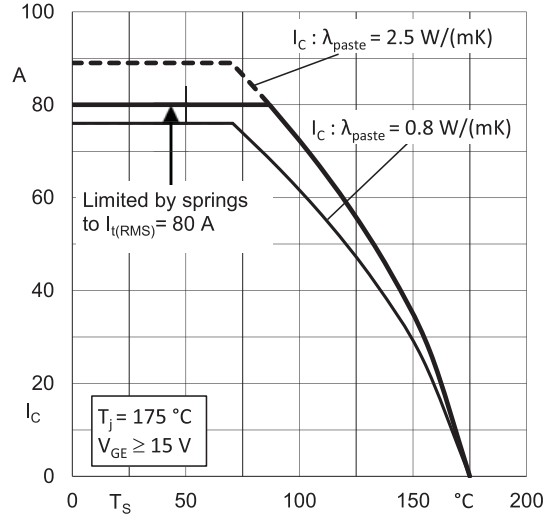


Fig. 2: Typ. rated current vs. temperature  $I_C = f(T_s)$

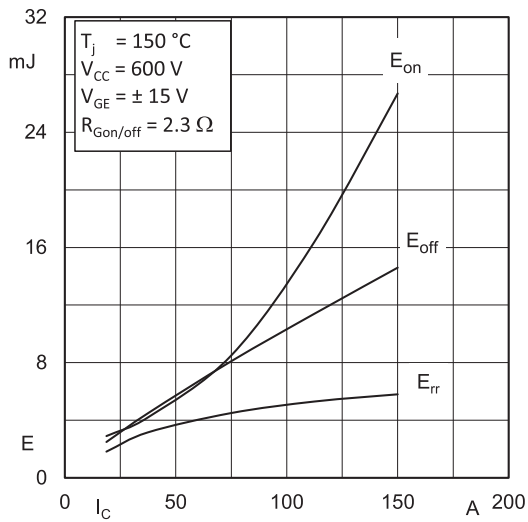


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$

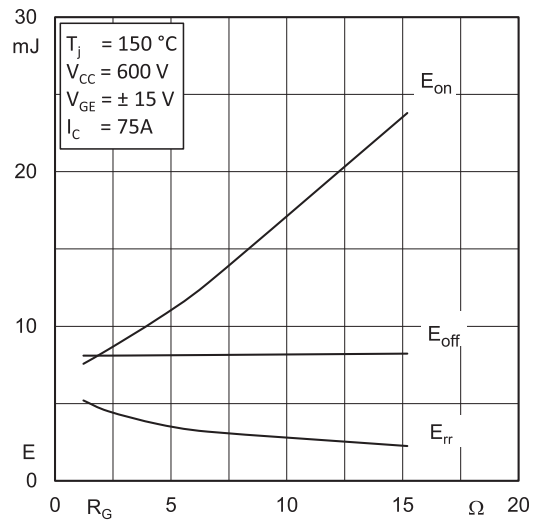


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

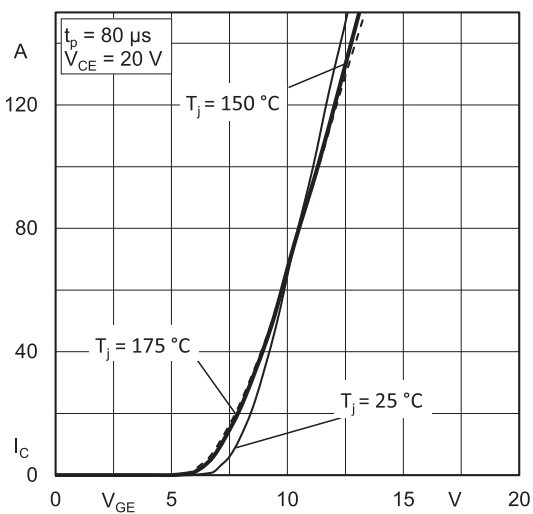


Fig. 5: Typ. transfer characteristic

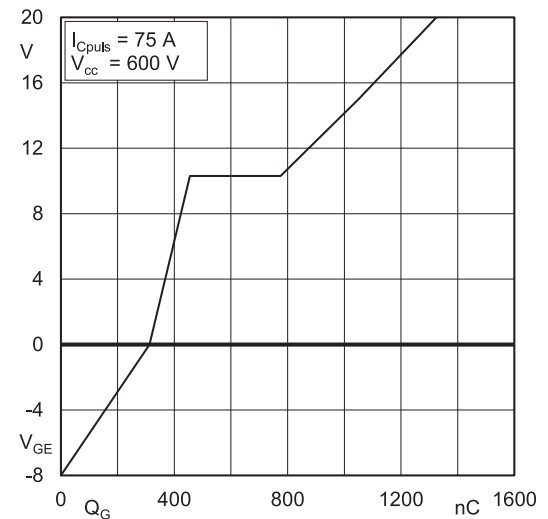


Fig. 6: Typ. gate charge characteristic

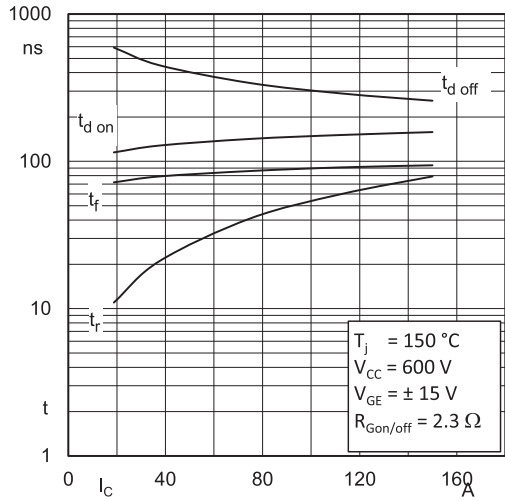


Fig. 7: Typ. switching times vs.  $I_C$

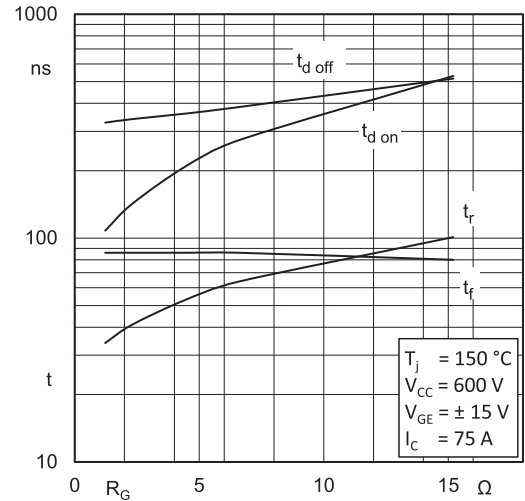


Fig. 8: Typ. switching times vs. gate resistor  $R_G$

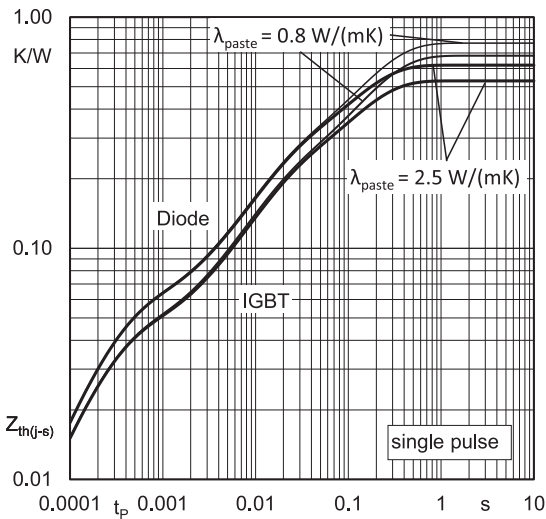


Fig. 9: Typ. transient thermal impedance

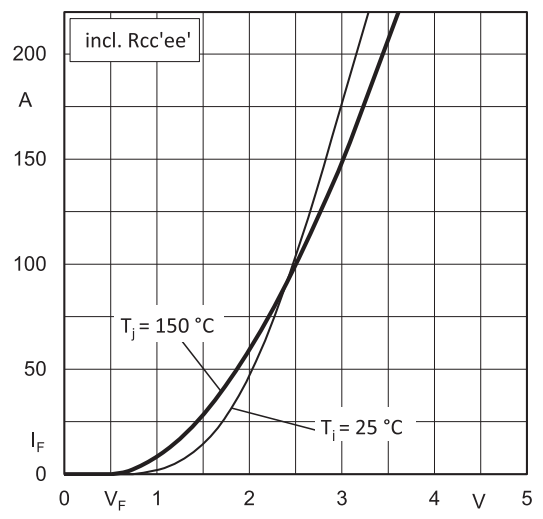


Fig. 10: Typ. CAL diode forward characteristic

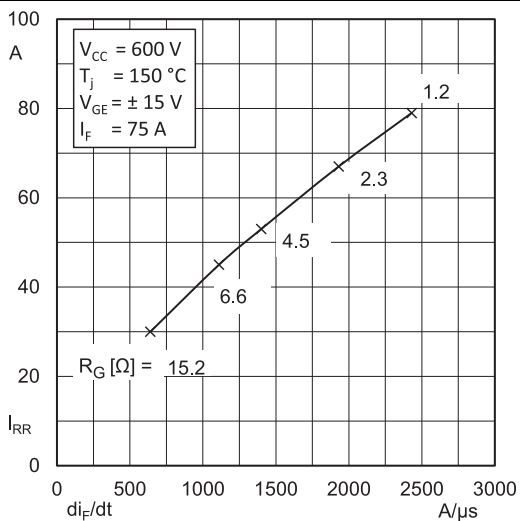


Fig. 11: Typ. CAL diode peak reverse recovery current

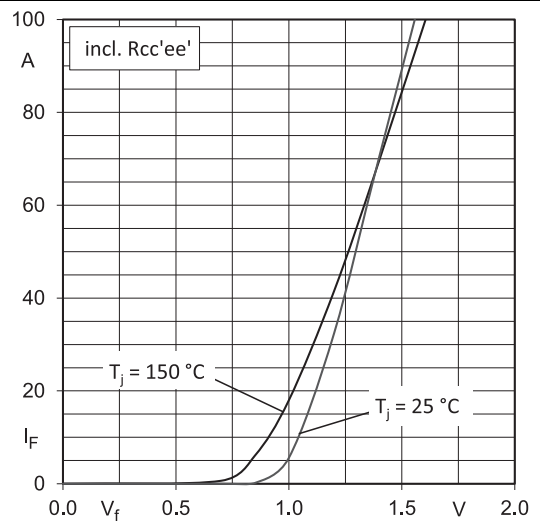
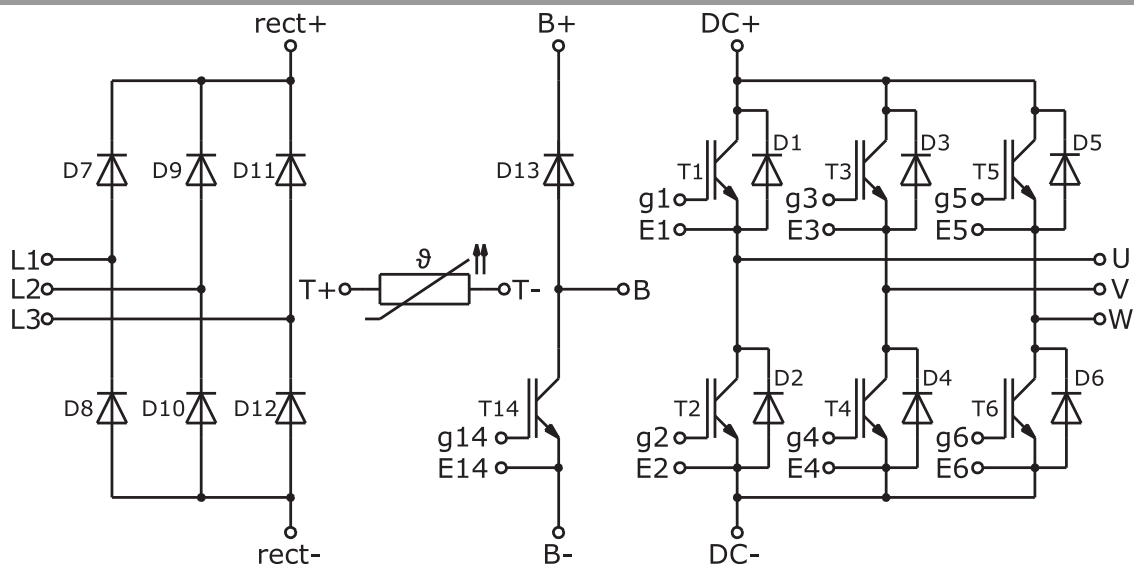


Fig. 12: Typ. input bridge forward characteristic







Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

### \*IMPORTANT INFORMATION AND WARNINGS

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